

## Military Logic Products

## FEATURES

- Four edge-triggered D flip-flops
- Buffered common Clock
- Buffered, asynchronous Master Reset
- True and complementary output

## DESCRIPTION

The 54F175 is a quad, edge-triggered D-type flip-flop with individual D inputs and both Q and  $\bar{Q}$  outputs. The common buffered Clock (CP) and Master Reset (MR) inputs load and reset (clear) all flip-flops simultaneously.

## Quad D Flip-Flop

## Product Specification

The register is fully edge-triggered. The state of each D input, one setup time before the Low-to-High clock transition, is transferred to the corresponding flip-flop's Q output.

All Q outputs will be forced LOW independently of Clock or Data inputs by a Low voltage level on the MR input. The device is useful for applications where both true and complement outputs are required, and the Clock and Master Reset are common to all storage elements.

## ORDERING INFORMATION

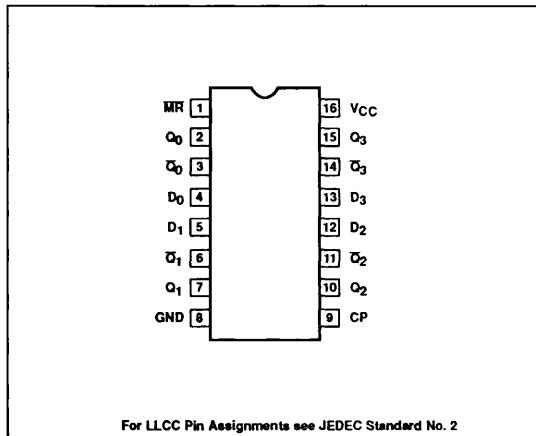
DESCRIPTION	ORDER CODE
Ceramic DIP	54F175/BEA
Ceramic Flat Pack	54F175/BFA
Ceramic LLCC	54F175/B2A

## INPUT AND OUTPUT LOADING AND FAN-OUT TABLE

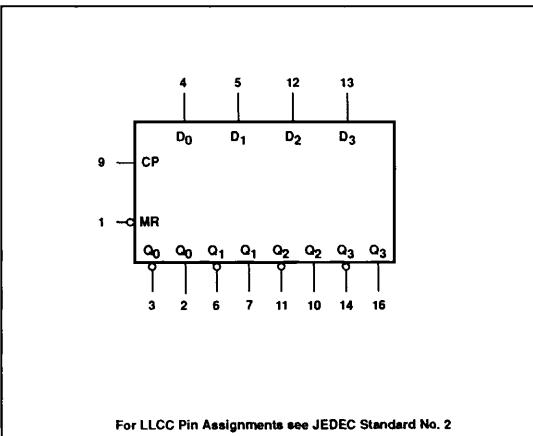
PINS	DESCRIPTION	54F (U.L.) HIGH/LOW	LOAD VALUE HIGH/LOW
D <sub>0</sub> - D <sub>3</sub>	Data inputs	1.0/1.0	20µA/0.6mA
CP	Clock pulse input (active rising edge)	1.0/1.0	20µA/0.6mA
MR	Master Reset input (active Low)	1.0/1.0	20µA/0.6mA
Q <sub>0</sub> - Q <sub>3</sub>	True outputs	50/33	1.0mA/20mA
$\bar{Q}_0$ - $\bar{Q}_3$	Complementary outputs	50/33	1.0mA/20mA

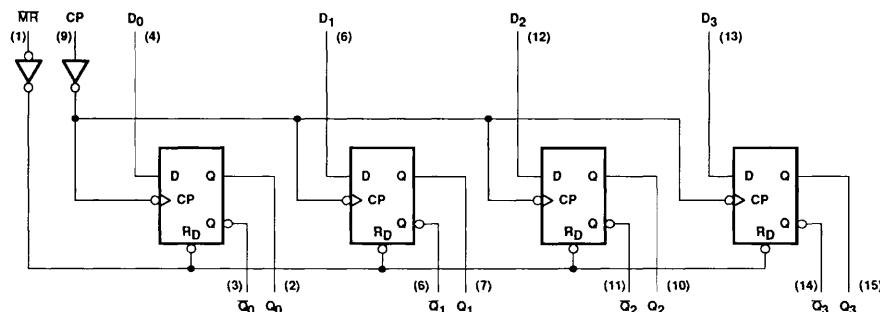
NOTE: One (1.0) FAST Unit Load (U.L.) is defined as: 20µA in the High state and 0.6mA in the Low state.

## PIN CONFIGURATION



## LOGIC SYMBOL



**Flip-Flop****54F175****LOGIC DIAGRAM**

For LLCC pin assignment, see JEDEC Standard No. 2.

**FUNCTION TABLE**

OPERATING MODE	INPUTS			OUTPUTS	
	MR	CP	D <sub>n</sub>	Q <sub>n</sub>	Q̄ <sub>n</sub>
Reset (clear)	L	X	X	L	H
Load "1"	H	↑	h	H	L
Load "0"	H	↑	l	L	H

H = High voltage level steady state.

h = High voltage level one setup time prior to the Low-to-High Clock transition.

L = Low voltage level steady state.

I = Low voltage level one setup time prior to the Low-to-High Clock transition.

X = Don't Care.

↑ = Low-to-High Clock transition.

**ABSOLUTE MAXIMUM RATINGS** (Operation beyond the limits set forth in this table may impair the useful life of the device.  
Unless otherwise noted these limits are over the operating free-air temperature range.)

SYMBOL	PARAMETER	RATING			UNIT
		Min	Nom	Max	
V <sub>CC</sub>	Supply voltage range	-0.5	to +7.0		V
V <sub>I</sub>	Input voltage range	-0.5	to +7.0		V
I <sub>I</sub>	Input current range	-30	to +5.0		mA
V <sub>O</sub>	Voltage applied to output in High output state range	-0.5	to +V <sub>CC</sub>		V
I <sub>O</sub>	Current applied to output in Low output state		40		mA
T <sub>STG</sub>	Storage temperature range	-65	to +150		°C

**RECOMMENDED OPERATING CONDITIONS**

SYMBOL	PARAMETER	LIMITS			UNIT
		Min	Nom	Max	
V <sub>CC</sub>	Supply voltage	4.5	5.0	5.5	V
V <sub>IH</sub>	High-level input voltage		2.0		V
V <sub>IL</sub>	Low-level input voltage			0.8	V
I <sub>IK</sub>	Input clamp current			-18	mA
I <sub>OH</sub>	High-level output current			-1	mA
I <sub>OL</sub>	Low-level output current			20	mA
T <sub>A</sub>	Operating free-air temperature range	-55		+125	°C

**Flip-Flop****54F175****DC ELECTRICAL CHARACTERISTICS** (Over recommended operating free-air temperature range unless otherwise noted.)

SYMBOL	PARAMETER	TEST CONDITIONS <sup>1,4</sup>	LIMITS			UNIT
			Min	Typ <sup>2</sup>	Max	
V <sub>OH</sub>	High-level output voltage	V <sub>CC</sub> = Min, V <sub>IL</sub> = Max, I <sub>OH</sub> = Max, V <sub>IH</sub> = Min	2.5			V
V <sub>OL</sub>	Low-level output voltage	V <sub>CC</sub> = Min, V <sub>IL</sub> = Max, I <sub>OL</sub> = Max, V <sub>IH</sub> = Min		0.35	0.50	V
V <sub>IK</sub>	Input clamp voltage	V <sub>CC</sub> = Min, I <sub>I</sub> = I <sub>IK</sub>		-0.73	-1.2	V
I <sub>IH2</sub>	Input current at maximum input voltage	V <sub>CC</sub> = Max, V <sub>I</sub> = 7.0V			100	µA
I <sub>IH1</sub>	High-level input current	V <sub>CC</sub> = Max, V <sub>I</sub> = 2.7V		1	20	µA
I <sub>IL</sub>	Low-level input current	V <sub>CC</sub> = Max, V <sub>I</sub> = 0.5V		-0.4	-0.6	mA
I <sub>OS</sub>	Short-circuit output current <sup>3</sup>	V <sub>CC</sub> = Max	-60		-150	mA
I <sub>CC</sub>	Supply current (total)	V <sub>CC</sub> = Max, D <sub>n</sub> = MR ≥ 4.0V, CP = ↑		25	34	mA

**AC ELECTRICAL CHARACTERISTICS** (When measured in accordance with the procedures outlined in Signetics LOGIC App Note 202, "Testing and Specifying FAST Logic.")

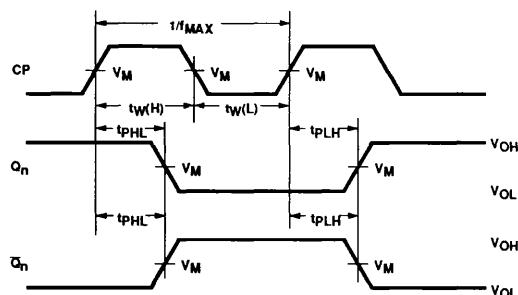
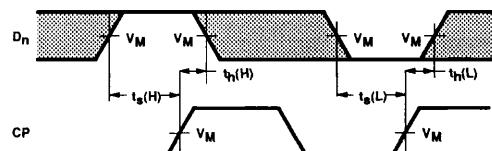
SYMBOL	PARAMETER	TEST CONDITIONS	LIMITS					UNIT	
			TA = +25°C V <sub>CC</sub> = +5.0V C <sub>L</sub> = 50pF, R <sub>L</sub> = 500Ω			TA = -55°C to +125°C V <sub>CC</sub> = +5.0V ± 10% C <sub>L</sub> = 50pF, R <sub>L</sub> = 500Ω			
			Min	Typ	Max	Min	Max		
			100	140		80 <sup>5</sup>		MHz	
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation delay CP to Q <sub>n</sub> or Q̄ <sub>n</sub>	Waveform 1	4.0 4.0	5.0 6.5	6.5 8.5	3.5 4.0	8.5 10.5	ns ns	
t <sub>PHL</sub>	Propagation delay MR to Q <sub>n</sub>	Waveform 3	4.5	9.0	11.5	4.5	15	ns	
t <sub>PLH</sub>	Propagation delay MR to Q̄ <sub>n</sub>	Waveform 3	4.0	6.5	8.0	4.0	10	ns	

**NOTES:**

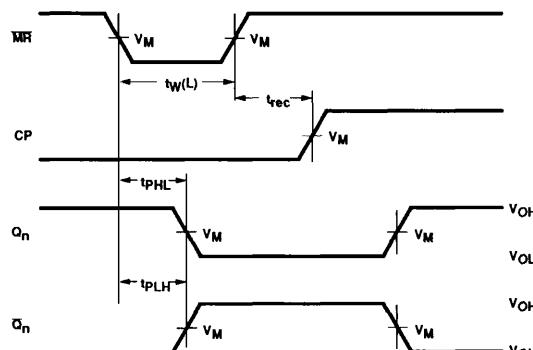
- For conditions shown as Min or Max, use the appropriate value specified under recommended operating conditions for the applicable type and function table operating mode.
- All typical values are at V<sub>CC</sub> = 5V, T<sub>A</sub> = 25°C.
- Not more than one output should be shorted at a time. For testing I<sub>OS</sub>, the use of high-speed test apparatus and/or sample-and-hold techniques are preferable in order to minimize internal heating and more accurately reflect operational values. Otherwise, prolonged shorting of a High output may raise the chip temperature well above normal and thereby cause invalid readings in other parameter tests. In any sequence of parameter tests, I<sub>OS</sub> tests should be performed last.
- When testing devices to the functional table specified refer to the "Recommended Operating Conditions Section" of Application Note 202, "Testing and Specifying FAST Logic".
- These parameters are guaranteed, but not tested.

**Flip-Flop****54F175****AC SETUP REQUIREMENTS**

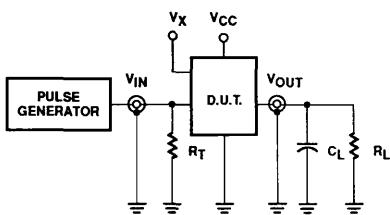
SYMBOL	PARAMETER	TEST CONDITIONS	LIMITS					UNIT	
			$T_A = +25^\circ\text{C}$ $V_{CC} = +5.0\text{V}$		$T_A = -55^\circ\text{C}$ to $+125^\circ\text{C}$ $V_{CC} = +5.0\text{V} \pm 10\%$				
			Min	Typ	Max	Min	Max		
$t_s(H)$ $t_s(L)$	Setup time, High or Low D <sub>n</sub> to CP	Waveform 2	3.0			3.0		ns	
$t_h(H)$ $t_h(L)$	Hold time, High or Low D <sub>n</sub> to CP	Waveform 2	1.0			1.0		ns	
$t_w(H)$ $t_w(L)$	CP pulse width, High or Low	Waveform 1	4.0			4.0		ns	
$t_w(L)$	MR pulse width Low	Waveform 3	5.0			5.0		ns	
$t_{rec}$	Recovery time MR to CP	Waveform 3	5.0			5.0		ns	

**AC WAVEFORMS**Waveform 1. Clock to Output Delays  
and Clock Pulse Width

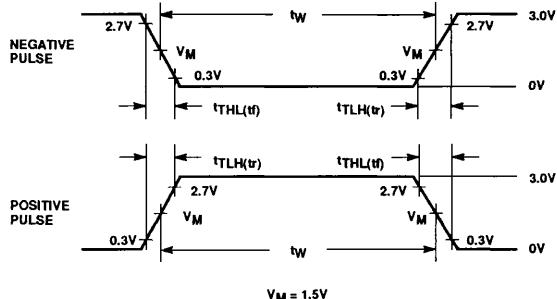
Waveform 2. Data Setup and Hold Times

Waveform 3. Master Reset to Output Delay,  
Master Reset Pulse Width, and Master Reset Recovery Time

NOTE: For all waveforms  $V_M = 1.5\text{V}$   
The shaded areas indicate when the input is permitted to change for predictable output performance.

**Flip-Flop****54F175****TEST CIRCUIT AND WAVEFORM****Test Circuit for Totem-Pole Outputs****DEFINITIONS:**

- $R_L$  = Load Resistor; see AC Characteristics for value.
- $C_L$  = Load capacitance includes jig and probe capacitance; see AC Characteristics for value.
- $R_T$  = Termination resistance should be equal to  $Z_{OUT}$  of pulse generators.
- $V_X$  = Unclocked pins must be held at:  $\leq 0.8V$ ;  $\geq 2.7V$  or open per FunctionTable.

**Input Pulse Definition**

INPUT PULSE CHARACTERISTICS				
Family	Rep. Rate	Pulse Width	$t_{TLH}$	$t_{THL}$
54F	1MHz	500ns	$\leq 2.5ns$	$\leq 2.5ns$